

ET3220

Epoxy Resin for LED Potting application

ET3220 is a versatile epoxy adhesive composed of two components that can be easily cured at room temperature once combined. It boasts a low mixing viscosity, making the potting process uncomplicated. Upon curing, it yields a smooth surface and is ideal for potting various substrates. This adhesive offers excellent mechanical strength, superior electrical insulation, and resistance to high and low temperatures. It meets both RoHS and REACH standards, making it suitable for potting GOB LED displays.

FEATURE

- Potting of various substrates
- GOB LED display potting
- Can be cured at room temperature with good toughness
- Good mechanical strength and impact resistance
- Excellent electrical properties, uniform light transmittance, and no discoloration
- Resistant to scratches and bumps, not easily damaged

TYPICAL UNCURED PROPERTIES

Properties	ET3220A	ET3220B
Appearance	Liquid	Liquid
Color	Colorless	Light yellow
Viscosity 25°C, S14 100rpm, cps	1500±500	250±100
Specific Gravity	1.07±0.1	1.06±0.1

TYPICAL CURING PROPERTIES *

Properties	ET3220
Mix Rate (A:B) By Weight	2:1
Mixed viscosity, 25°C, mPa·s	500±200
Pot Life, 25°C, min	>40
Tack-free Time, 25°C, hr	24
Through Cure Time, 65°C, min	60
Through Cure Time, 25 °C, day	5 ~ 7

DIRECTION OF USE

- The oxide layer, dust, moisture, oil, etc. on the surface of the base material will have a certain impact on the bonding strength of the base material. To obtain the best bonding performance, it is recommended that the surface of the bonded material should be cleaned.
- Mix components A and B in a mass ratio of 2:1, vacuum for 3 minutes, and then vacuum for 1 minute after dispensing.
- The good curing effect of all adhesives is related to many conditions, among which changes in the working environment are also very important factors. Therefore, in order to obtain the ideal curing effect, it is recommended to communicate with IBOX engineers and adjust the use process according to the conditions of the production line.
- During the curing process of the adhesive, it is recommended to use matching fixtures to support the parts. Do not allow the bonding substrate to move or become dislocated due to force dislocation before curing, which may cause the adhesive to fail to exert its maximum bonding strength.

TYPICAL CURED PROPERTIES *1

Properties	ET3220
Coefficient of thermal expansion, ASTM D696	α2: 46.4 ppm/°C
Water absorption @100°C/1h	0.33 %
Durometer Hardness, Shore D	50±5

STORAGE AND SHELF LIFE

Shelf life of this product is six months when stored below 14~34°C in original, unopened containers.

The data contained in this bulletin is provided only as a guide for evaluation/consideration. These material characteristics are typical properties that are based on a limited number of samples tested in the laboratory. We cannot assume responsibility for results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any product or method. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide.

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CAUTIONS

- Please store it away from children and use necessary protective equipment when using this product, such as respiratory masks, rubber gloves, labor protection clothing, etc., to prevent unknown adverse effects.
- Please close ET3220 Component B tightly after use to avoid deterioration and unusability.
- Please use up A and B in time after mixing, otherwise the operation and post-curing performance will be affected.
- If this product accidentally gets on your skin, please wash it immediately with soap and water.
- If it accidentally comes into contact with your eyes, please wash with plenty of water and then seek medical advice. Please refer to the MSDS of this product for details.
- When using this product, do not discard unused chemicals at will, otherwise it may cause accidents. Please refer to the MSDS of this product for disposal information.
- When using this product, the product used outside the box may be contaminated during use. To avoid contamination of unused glue, do not pour any glue back into the original packaging. The company will not be responsible for products that have been contaminated or have been stored improperly as mentioned above.

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